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Intel, Ericsson Expand Collaboration to Advance Next-Gen Optimized 5G Infrastructure

Intel to manufacture future custom 5G SoC for Ericsson on 18A process technology

NEWS HIGHLIGHTS

- Announcement signals confidence in 18A process technology and underscores progress on Intel's five-nodes-in-four-years roadmap to regain process leadership.
- News shows continued collaboration between the companies to optimize standard Intel® Xeon® Scalable processor-based platforms for Ericsson's Cloud RAN solutions.
- Industry leaders advance the adoption of 5G, building sustainable and resilient networks of the future.

SANTA CLARA, Calif.--(BUSINESS WIRE)-- Today, Intel announced a strategic collaboration agreement with Ericsson to utilize Intel's 18A process and manufacturing technology for Ericsson's future next-generation optimized 5G infrastructure.

As part of the agreement, Intel will manufacture custom 5G SoCs (system-on-chip) for Ericsson to create highly differentiated leadership products for future 5G infrastructure. Additionally, the companies will expand their collaboration to optimize 4th Gen Intel® Xeon® Scalable processors with Intel® vRAN Boost for Ericsson's Cloud RAN (radio access network) solutions to help communications service providers increase network capacity and energy efficiency while gaining greater flexibility and scalability.

"As our work together evolves, this is a significant milestone with Ericsson to partner broadly on their next-generation optimized 5G infrastructure. This agreement exemplifies our shared vision to innovate and transform network connectivity, and it reinforces the growing customer confidence in our process and manufacturing technology," said Sachin Katti, senior vice president and general manager of the Network and Edge group at Intel. "We look forward to working together with Ericsson, an industry leader, to build networks that are open, reliable and ready for the future."

18A is Intel's most advanced node on the company's five-nodes-in-four-years roadmap. After new gate-all-around transistor architecture – known as RibbonFET – and backside power delivery – called PowerVia – appear first in Intel 20A, Intel will deliver ribbon architecture innovation and increased performance along with continued metal linewidth reduction in 18A. Combined, these technologies will put Intel back in the process leadership position in 2025, elevating future offerings its customers bring to market.

"Ericsson has a long history of close collaboration with Intel, and we are pleased to expand this further as we utilize Intel to manufacture our future custom 5G SoCs on their 18A

process node, which is in line with Ericsson's long-term strategy for a more resilient and sustainable supply chain," said Fredrik Jejdling, executive vice president and head of Networks at Ericsson. "In addition, we will be expanding our collaboration that we announced at MWC 2023 to work together with the ecosystem to accelerate industry-scale open RAN utilizing standard Intel Xeon-based platforms."

The future is open and scalable

As 5G deployments continue, the future lies in fully programmable, open software-defined networks powered by the same cloud-native technologies that transformed the data center, delivering unparalleled agility and automation.

To realize the best performance, innovation and global scale, the industry needs to work together and continue to synchronize network specifications as part of one global set of standards. Intel and Ericsson collaborate with other leading technology companies to bring these benefits to their customers toward industry-scale open RAN.

About Intel

Intel (Nasdaq: INTC) is an industry leader, creating world-changing technology that enables global progress and enriches lives. Inspired by Moore's Law, we continuously work to advance the design and manufacturing of semiconductors to help address our customers' greatest challenges. By embedding intelligence in the cloud, network, edge and every kind of computing device, we unleash the potential of data to transform business and society for the better. To learn more about Intel's innovations, go to newsroom.intel.com and intel.com.

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